

CLAIMS

1. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth, said apparatus comprises a header and a waste gas treating trough mounted below said header and 5 having at the center thereof a reaction room, and is characterized by:

10 said reaction room is surrounded by a water receiving chamber outside of it, said water receiving chamber is provided on the top thereof with an annular spillway in communicating with said reaction room; water in said water receiving chamber is smoothly and uniformly distributed to said annular spillway, and spills to said reaction room to form an annular water wall on the wall of said reaction room.

15 2. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth, said apparatus comprises a header, a waste gas treating trough and an annular guide in which said waste gas treating trough is mounted below said header and has at the center thereof a reaction room, said apparatus is characterized by:

20 said reaction room is surrounded by a water receiving chamber outside of it, said water receiving chamber is provided on the top thereof with an annular spillway in communicating with said reaction room; and said annular guide is mounted at said annular spillway, by guiding of said annular guide, water is smoothly and uniformly distributed to said annular spillway, and spills to said reaction room to form an annular water wall on the wall of said reaction room.

25 3. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 2, wherein, said water receiving chamber is provided with a water inlet and a water

discharge outlet.

4. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 2, wherein,

a sensing probe is provided in said annular spillway to detect whether

5 there is water entering said water receiving chamber.

5. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 2, wherein,

said header is provided with a sensing probe used to sense the reaction temperature in a reaction room.

10 6. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 5, wherein,

said sensing probe is provided therearound with a plurality of hydrogen spraying nozzles and a plurality of waste gas delivery pipes for delivering hydrogen and semiconductor waste gas.

15 7. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 6, wherein,

said hydrogen spraying nozzles are provided each with a fire spraying port on the front end thereof.

8. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 2, wherein,

said annular spillway is provided with no sensing probe.

9. A semiconductor waste-gas treating apparatus having the ability of preventing sedimentation and etching of filth as claimed in claim 2, wherein,

said annular guide is provided on the top thereof with an annular flange.